

Switch, N-Chanel MMBF4093

Features

- This Device is Designed for Low Level Analog Switching Applications, Sample and Hold Circuits and Chopper Stabilized Amplifiers.
- Sourced from Process 51.
- This is a Pb-Free and a Halide Free Device

ABSOLUTE MAXIMUM RATINGS (Note 1), (Note 2)

(T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DG}	Drain-Gate Voltage	40	V
V_{GS}	Gate-Source Voltage	-40	V
I _{GF}	Forward Gate Current	50	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to + 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. onsemi should be consulted on applications involving pulsed or low-duty cycle operations.

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Characteristic	Max	Unit
P_{D}	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
R _θ JA	Thermal Resistance, Junction to Ambient (Note 3)	357	°C/W

3. Device mounted on FR-4 PCB 1.6" \times 1.6" \times 0.06".



SOT-23 CASE 318-08

Note: Source & Drain are interchangeable

MARKING DIAGRAM



61L = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBF4093	SOT-23 (Pb-Free)	3000 / Tape and Real

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MMBF4093

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter Test Conditions		Min	Max	Unit
FF CHARAC	TERISTICS			•	
V _{(BR)GSS}	Gate-Source Breakdown Voltage	$I_{G} = 1 \mu A, V_{DS} = 0$	-40	_	V
V _{GS} (off)	Gate-Source Cut-Off Voltage	V _{DS} = 20 V, I _D = 1 nA	-1.0	-5.0	V
I _{DGO}	I_{DGO} Drain-Gate Leakage Current $V_{DG} = 20 \text{ V, } I_S = 0$ $V_{DG} = 20 \text{ V, } I_S = 0, T_A = 150^{\circ}\text{C}$		- -	-200 -400	pA nA
I _D (off)	Drain Cutoff Leakage Current	V _{DS} = 20 V, V _{GS} = -6 V V _{DS} = 20 V, V _{GS} = -6 V, T _A = 150°C	_ _	200 400	pA nA
N CHARACT	ERISTICS	•			
I _{DSS}	Zero-Gate Voltage Drain Current (Note 4)	V _{DS} = 20 V, I _{GS} = 0	8	_	mA
V _{DS} (on)	Drain-Source On Voltage	I _D = 2.5 mA, V _{GS} = 0	-	0.2	V
r _{DS} (on)	on) Drain-Source On Resistance $I_D = 1 \text{ mA}, V_{GS} = 0$		-	80	Ω
MALL SIGNA	AL CHARACTERISTICS				
r _{DS} (on)	Drain-Source On Resistance	V _{DS} = V _{GS} = 0, f = 1 kHz	_	80	Ω
C _{iss}	Input Capacitance	V _{DS} = 20 V, V _{GS} = 0 V, f = 1.0 MHz	_	16	pF
C _{rss}	Reverse Transfer Capacitance	V _{DS} = -20 V, f = 1.0 MHz	-	5	pF
WITCHING C	HARACTERISTICS				
t _{On}	Turn-On Time	I _{D(on)} = 3.0 mA	-	60	ns
t _{Off}	Turn-Off Time	V _{GS(off)} = 3.0 V	-	80	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1%.

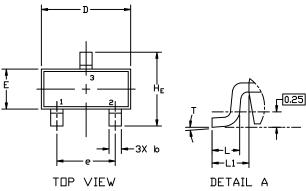




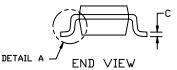
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DATE 01 MAR 2023









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°



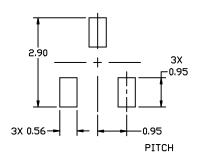


XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



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STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: I PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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